

Description

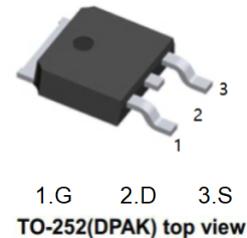
The Power MOSFET is fabricated using the advanced planar VDMOS technology. The resulting device has low conduction resistance, superior switching performance and high avalanche energy.

Features

- Low $R_{DS(on)}$
- Low gate charge (typ. $Q_g = 9.5\text{nC}$)
- 100% UIS tested
- RoHS compliant

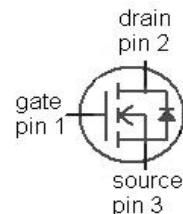
Product Summary

- $V_{DSS} = 500\text{V}$
- $I_D = 5\text{A}$
- $R_{DS(on)} = 2.4\Omega$



Applications

- Power factor correction.
- Switched mode power supplies.
- LED driver.



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	500	V
Continuous drain current ¹⁾ ($T_C = 25^\circ\text{C}$)	I_D	5	A
		2.5	A
Pulsed drain current ²⁾	I_{DM}	15	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ³⁾	E_{AS}	106	mJ
Power Dissipation	P_D	76	W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$
Continuous diode forward current	I_S	5	A
Diode pulse current	$I_{S,pulse}$	15	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.65	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient, minimal footprint ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Soldering temperature, wave soldering only allowed at leads. (1.6mm from case for 10s)	T_{sold}	260	$^\circ\text{C}$

Electrical Characteristics $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=0.25\text{mA}$	500	-	-	V
Gate threshold voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=0.25\text{mA}$	2.0	-	4.0	V
Drain cut-off current	I_{DSS}	$\text{V}_{\text{DS}}=500\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_j = 25^\circ\text{C}$	-	-	1	μA
Gate leakage current, Forward	I_{GSSF}	$\text{V}_{\text{GS}}=30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	100	nA
Gate leakage current, Reverse	I_{GSSR}	$\text{V}_{\text{GS}}=-30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	-100	nA
Drain-source on-state resistance	$\text{R}_{\text{DS}(\text{on})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=2\text{A}$	-	2.05	2.4	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$\text{V}_{\text{DS}} = 25\text{V}, \text{V}_{\text{GS}} = 0\text{V},$ $f = 250\text{kHz}$	-	391	-	pF
Output capacitance	C_{oss}		-	38.3	-	
Reverse transfer capacitance	C_{rss}		-	2.5	-	
Turn-on delay time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}} = 250\text{V}, \text{I}_D = 4\text{A}$ $\text{R}_G = 10\Omega, \text{V}_{\text{GS}}=10\text{V}$	-	9.9	-	ns
Rise time	t_r		-	29.9	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	15.7	-	
Fall time	t_f		-	7.6	-	
Gate charge characteristics						
Gate to source charge	Q_{gs}	$\text{V}_{\text{DD}}=400\text{V}, \text{I}_D=2\text{A}$ $\text{V}_{\text{GS}}=0\text{ to }10\text{V}$	-	1.9	-	nC
Gate to drain charge	Q_{gd}		-	4.3	-	
Gate charge total	Q_g		-	9.5	-	
Gate plateau voltage	$\text{V}_{\text{plateau}}$		-	4.9	-	V
Reverse diode characteristics						
Diode forward voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_F=7\text{A}$	-	-	1.3	V
Reverse recovery time	t_{rr}	$\text{V}_R=400\text{V}, \text{I}_F=5\text{A},$ $d\text{I}_F/dt=100\text{ A}/\mu\text{s}$	-	248	-	ns
Reverse recovery charge	Q_{rr}		-	1263.5	-	μC
Peak reverse recovery current	I_{rrm}		-	7.3	-	A

Notes:

1. Drain current limited by maximum junction temperature and duty cycle.
2. Repetitive Rating: Pulse width limited by maximum junction temperature, maximum duty cycle is 0.7.
3. $\text{I}_{\text{AS}}=4.6\text{A}, \text{L}=10\text{mH}, \text{V}_{\text{DD}}=60\text{V}, \text{Starting T}_j = 25^\circ\text{C}$.
4. The value of R_{thJA} is measured by placing the device in a still air box which is one cubic foot.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

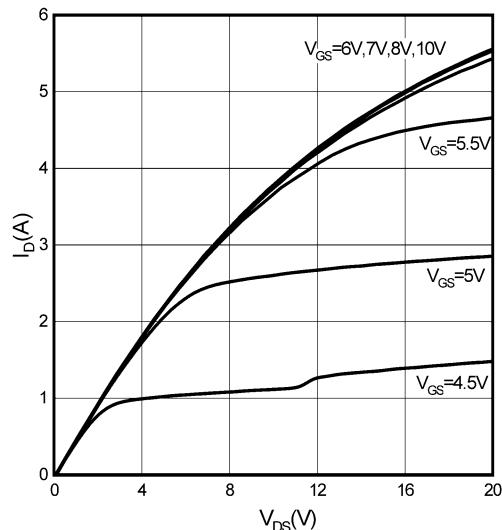


Figure 3. On-Resistance vs. Drain Current

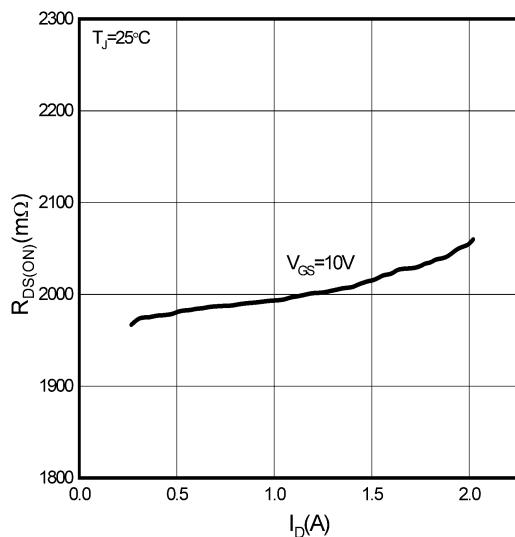


Figure 5. Breakdown Voltage vs. Temperature

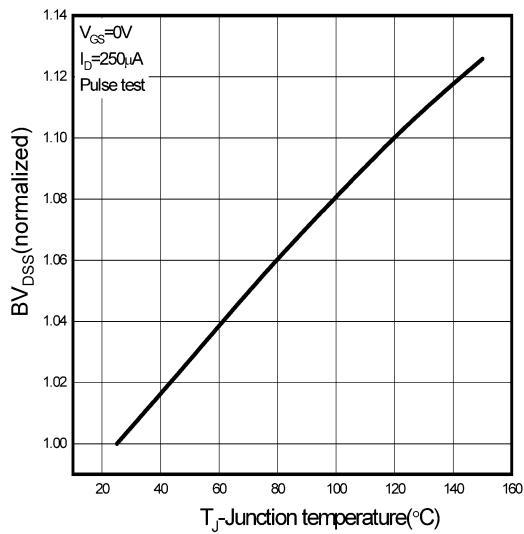


Figure 2. Transfer Characteristics

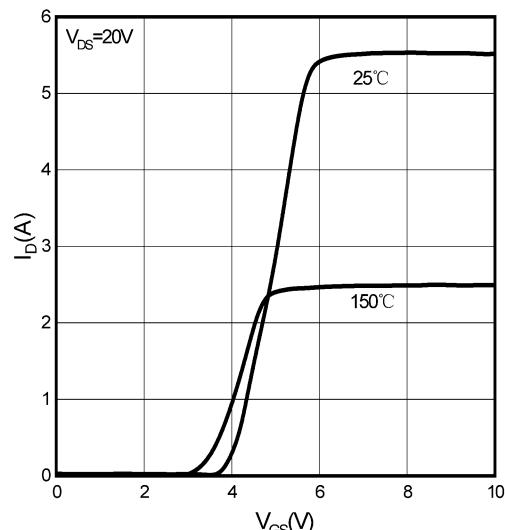


Figure 4. On-Resistance vs. Temperature

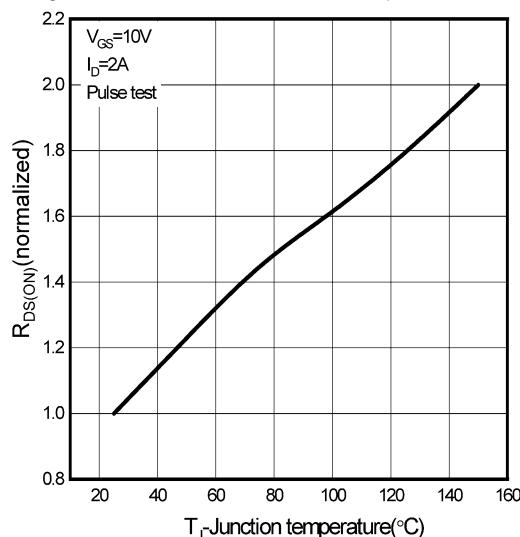


Figure 6. Threshold Voltage vs. Temperature

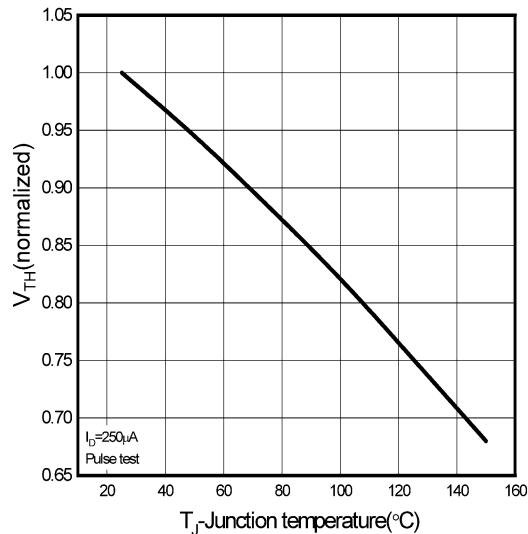


Figure 7.R_{ds(on)} vs. Gate Voltage

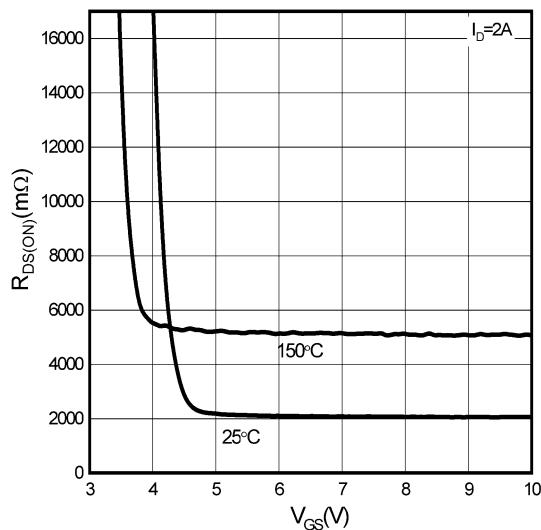


Figure 8.Body-Diode Characteristics

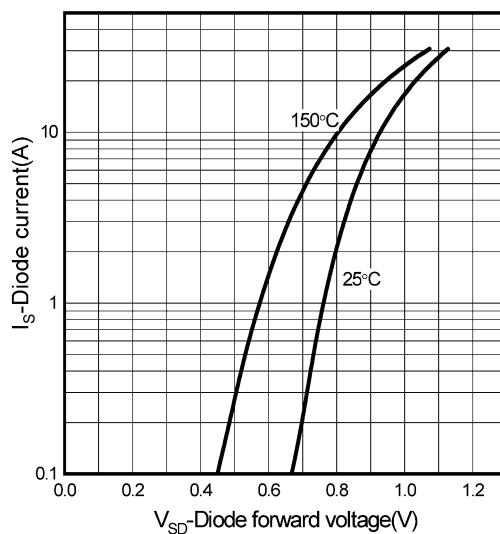


Figure 9.Capacitance Characteristics

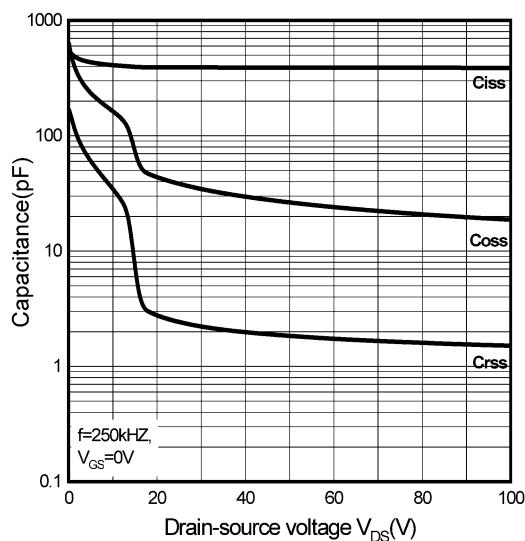


Figure 10.Gate Charge Characteristics

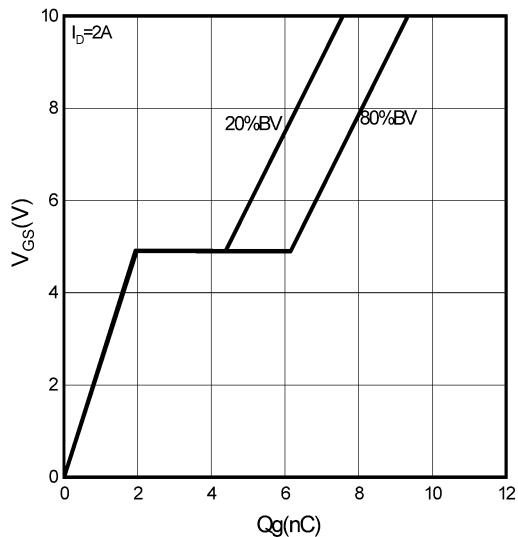


Figure 11.Drain Current Derating

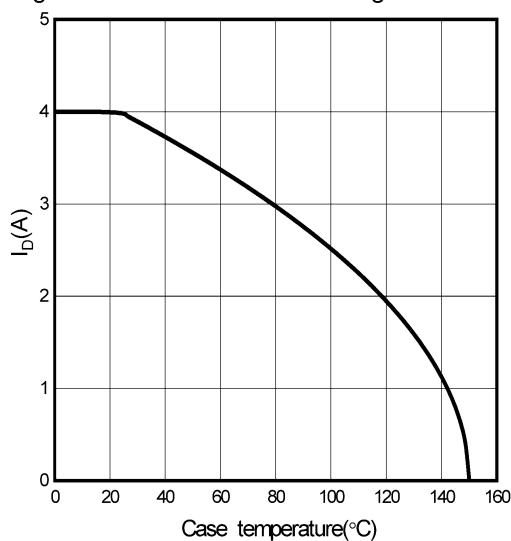


Figure 12.Power Dissipation vs.Temperature

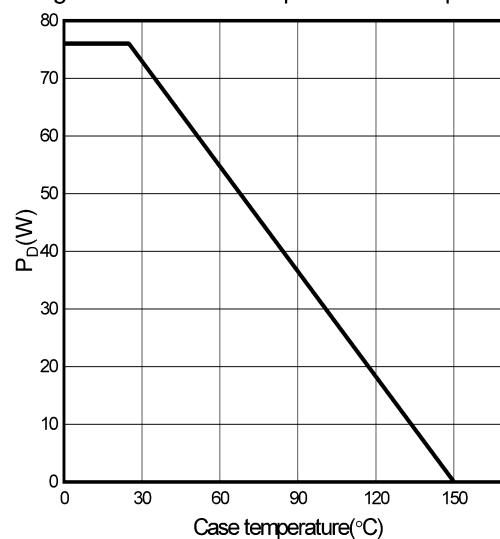
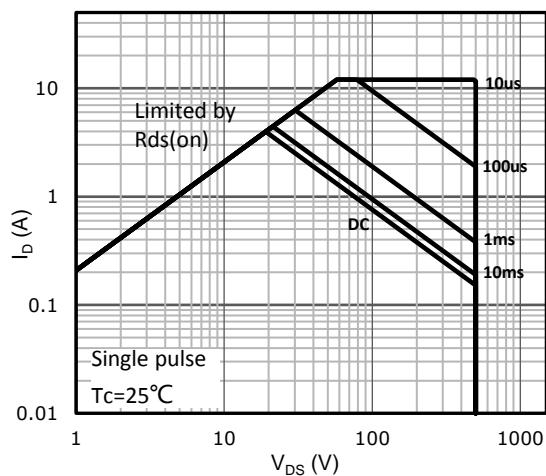
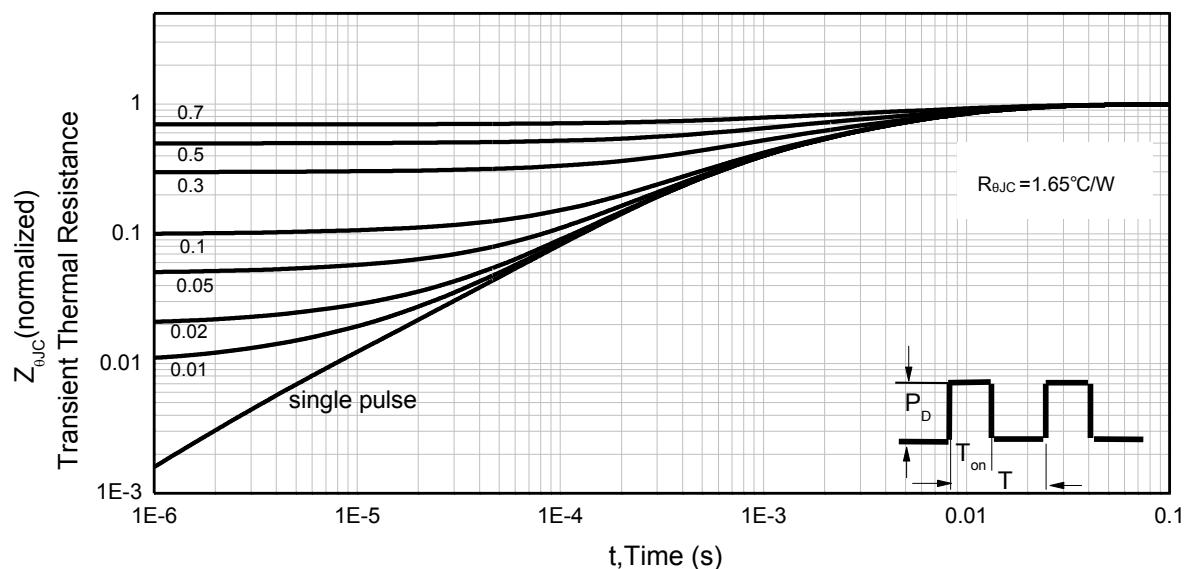
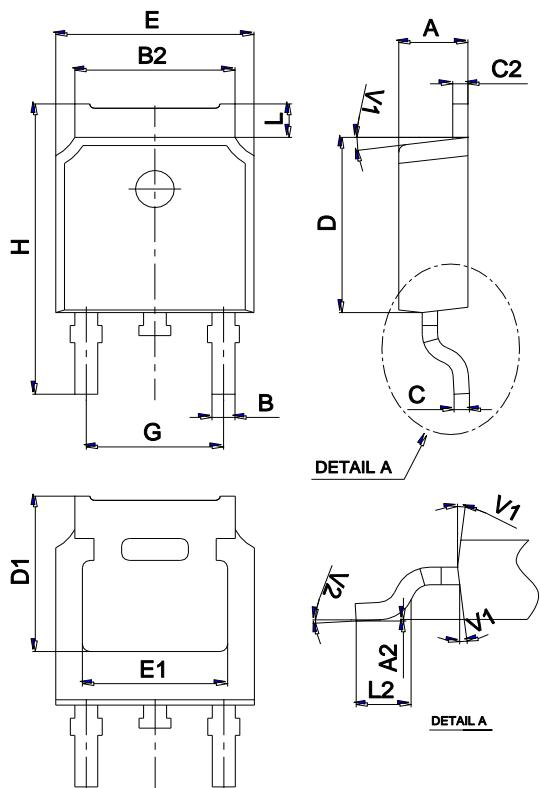
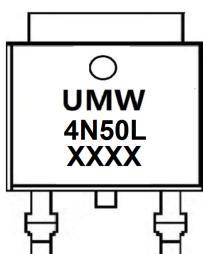


Figure 13. Safe Operating Area

Figure 14. Normalized Maximum Transient Thermal Impedance (R_{thJC})

Package Mechanical**Data TO-252**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Marking**Ordering information**

Order code	Package	Baseqty	Deliverymode
UMW 4N50L	TO-252	2500	Tape and reel